EPO-TEK® MED-354-T2

Technical Data Sheet
For Reference Only
Biocompatible/Thixotropic Epoxy
ISO 10993-5 Tested/Compliant

Date:	September 2025	
Rev:	II	
No. of Components:	Two	
Mix Ratio by Weight:	10 : 1	
Specific Gravity:	Part A: 1.12	Part B: 1.18
Pot Life:	3 Days	
Shelf Life- Bulk:	Six months at room temperature	

Biocompatible Certified Cure: 150°C / 45 Minutes

Alternative biocompatible cure schedules may be possible, but have not been certified. Contact med@epotek.com with any questions.

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Component suppliers assure Epoxy that all components are supplied in compliance with ISO 22442. Sales of EPO-TEK® MED-354-T2 shall accordingly require Epoxy's Standard Specification document to be signed as a technical agreement thereunder.

Product Description: EPO-TEK® MED-354-T2 is a biocompatible, high Tg, thixotropic version of EPO-TEK® MED-354-2 epoxy. It is electrically and thermally insulating and formulated for medical applications with fiber optics, optoelectronic assemblies, as well as semiconductor packaging.

Typical Properties: Cure condition: 150°C / 45 Minutes Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification
Information is Preliminary While Specifications Are Being Developed. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
*Color (before cure):	Part A: Tan	Part B: Dark Amber
*Consistency:	Smooth thixotropic paste	
*Viscosity (23°C) @ 20 rpm:	20,008	cPs
Thixotropic Index:	2.85	
*Glass Transition Temp:	111	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	68.6	x 10^{-6} in/in°C
Above Tg:	393.7	x 10^{-6} in/in°C
Shore D Hardness:	82	
Lap Shear @ 23°C:	1854	psi
Die Shear @ 23°C:	≥20	Kg 7,112 psi
Degradation Temp:	430	°C
Weight Loss:		
@ 200°C:	0.02	%
@ 250°C:	0.17	%
@ 300°C:	0.45	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	286,739.6	psi
Particle Size:	N/A	microns

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